

RH-SG150S

导热膏 Thermal Gap Filler

Features and Benefits

特点与优势

- ✳ High thermal conductivity: 1.5W/m-K
导热系数: 1.5W/M-K
- ✳ It is widely used in sensitive electronic components
广泛应用于敏感电子元件
- ✳ Easy to operate. It can be painted by hand or dispensing equipment
便于操作.可通过手工方式或点胶设备来进行涂装



RH-SG150S Thermal paste is suitable for CPU / GPU and other high thermal power modules. It is suitable for the mechanism with high thermal conductivity. Long term use of viscosity stability, viscosity will not be reduced, increased liquidity. Non conductive, not easy to produce moisture after use, moderate viscosity, easy to smear, easy to wipe. No corrosion, oxidation resistance, no effect on contact metal, not easy to solidify. Non toxic, tasteless, low mobility, not easy to cause environmental pollution

RH-SG150S 导热膏适用于 CPU/GPU 等高热功率模块。适用于热导率要求高的机构。长期使用粘度稳定, 粘度不会降低, 流动性增加。不导电, 使用后不易产生水分, 粘度适中, 易涂抹, 易擦拭。无腐蚀、抗氧化, 对接触金属无影响, 不易凝固。无毒、无味、流动性低, 不易造成环境污染。

The above suggestions and data are based on information that we believe to be reliable. Therefore, these suggestions and data are only for reference, not as product guarantee. It is up to the customer to decide whether the product is suitable or suitable for special use. We recommend that users first determine the suitability of our materials and recommendations before using them in large quantities.

以上建议及数据均来自我们认为可靠的资料。因此这些建议及数据仅供参考, 而不作为产品保证。应由客户决定产品是否合适或适用特殊用途。我们建议用户在大量使用前, 首先确定我们的材料适用性和建议。

RH-SG150S

Property	Parameter	Unit	Test Method
Color 颜色 (200°C/24H)	白色 White	--	Visual
Thermal Conductivity 导热系数	>1.5	W/m.k	ROCT8.140-82
Thermal Impedance 热阻抗 (25°C)	<0.14	°C*in ² /W	ROCT8.140-82
Specific Gravity 比重 (25°C)	>2.6	--	ASTM D1457
Evaporation 蒸发量 (200°C/24H)	<0.001	%	Fed.Std.791
Bleed 渗油量 (200°C/24H)	<0.05	%	Fed.Std.791
Dielectric Constant 绝缘常数 (100Hz)	>5.1	--	ASTM D150
Dissipation Factor 耗散系数 (100Hz)	<0.005	--	ASTM D150
Viscosity 粘度值 (25°C)	76	CPS	GB/T-10247
Thixotropic Index 锥入度 (25°C)	380	±10°	GB/T-269
Fire Rating 防火等级	V-0	--	UL94
Working Temperature 工作温度	-50~220	°C	--
RoHS/REACH	Compliance	--	--

使用 ASTM D5470 测试夹具,记录值包括界面热阻,数值仅供参考。实际应用性能到所施加的表面粗糙度、平整度和压力。注:厚度公差:±10%, 硬度公差:±5°, 颜色/厚度/硬度均可按顾客需求调试。

Applications

典型应用

- ✳ Suitable for high performance CPU / GPU 适用于高性能 CPU/GPU
- ✳ Hard disk, mobile phone, laptop 硬盘、手机、笔记本电脑
- ✳ Mobile and communication equipment 移动及通讯设备
- ✳ Automobile engine control equipment 汽车发动机控制设备
- ✳ Medical electronics, optical precision equipment 医疗电子,光学精密设备

Storage & Transportation: Store in a well ventilated, cool and dry place. Do not touch open fire. Store at 15-25 °C. This product is non-toxic and is stored and transported as non dangerous goods.

储存&运输: 贮存于通风、阴凉、干燥处, 不要接触明火, 贮存温度 (15-25 度)。本产品无毒, 按非危险品贮存及运输。

Packaging: Syringe: 0.5-50g, canned: 500g, 1000g, barreled: 5kg, 10kg, 20kg
包装: 针管装: 0.5-50g 罐装: 500g, 1000g, 桶装: 5KG,10KG,20KG

Safety: please refer to material safety performance data (MSDS) of our company

安全: 请参阅本公司《材料安全性能数据 (MSDS)》

Period of validity: the product is valid for 12 months

有效期: 本产品有效期为 12 个月